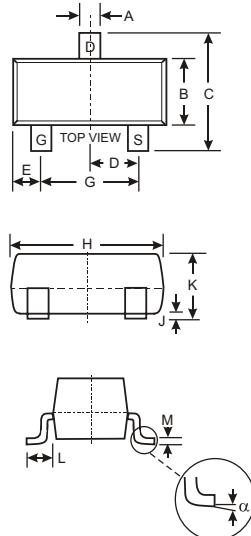
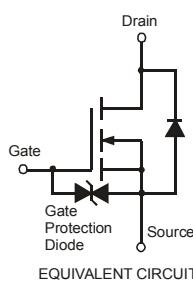


N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- ESD protected.
- Marking Code:SK



| SOT-23 | | |
|----------------------|-------|-------|
| Dim | Min | Max |
| A | 0.37 | 0.51 |
| B | 1.20 | 1.40 |
| C | 2.30 | 2.50 |
| D | 0.89 | 1.03 |
| E | 0.45 | 0.60 |
| G | 1.78 | 2.05 |
| H | 2.80 | 3.00 |
| J | 0.013 | 0.10 |
| K | 0.903 | 1.10 |
| L | 0.45 | 0.61 |
| M | 0.085 | 0.180 |
| α | 0° | 8° |
| All Dimensions in mm | | |

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Limit | Unit |
|--|----------------|------------|------|
| Drain-Source Voltage | V_{DS} | 50 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 0.22 | A |
| Drain Current-Pulsed (Note 1) | I_{DM} | 0.88 | A |
| Maximum Power Dissipation | P_D | 0.35 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | °C |

Thermal Characteristic

| | | | |
|--|-----------------|-----|------|
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 350 | °C/W |
|--|-----------------|-----|------|



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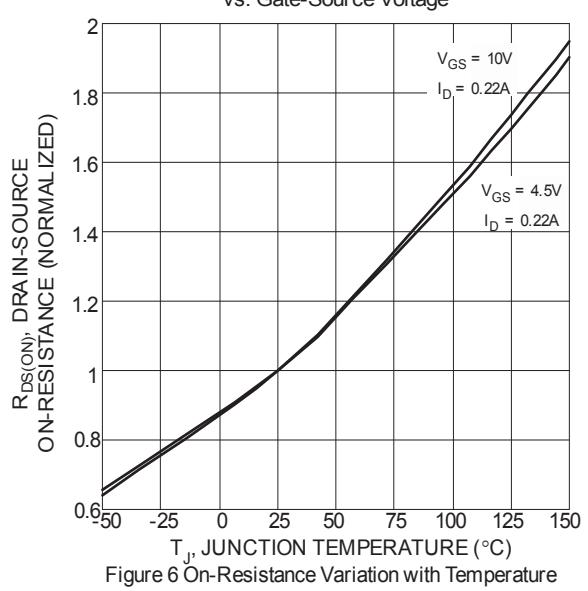
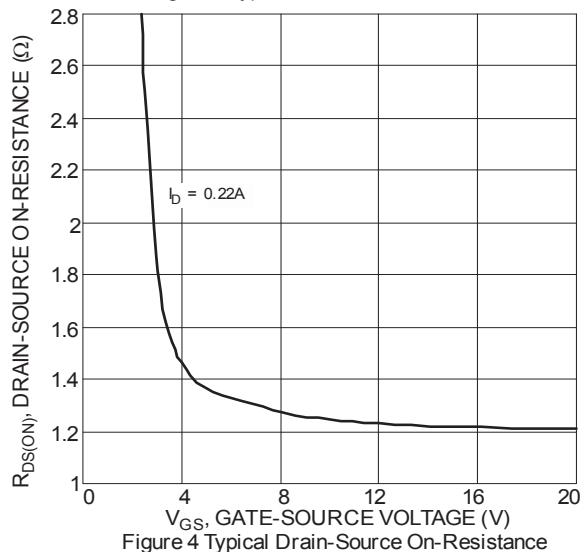
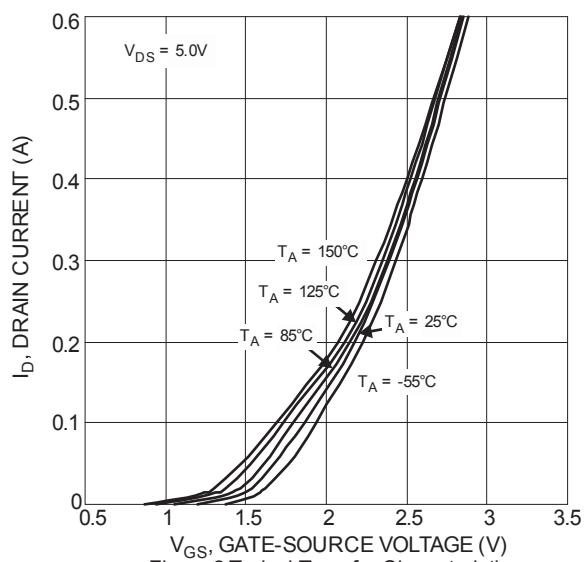
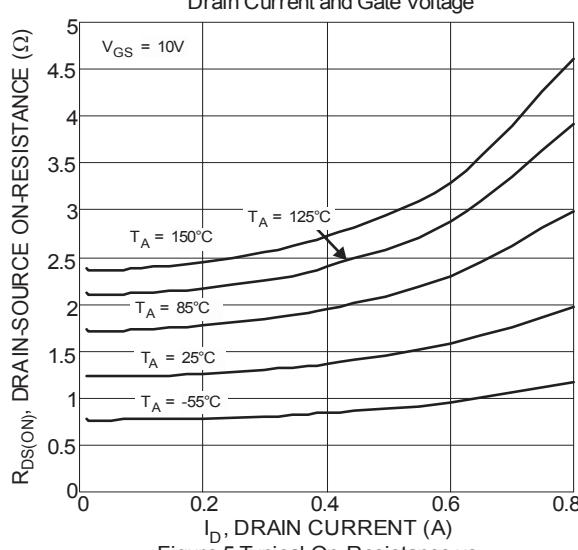
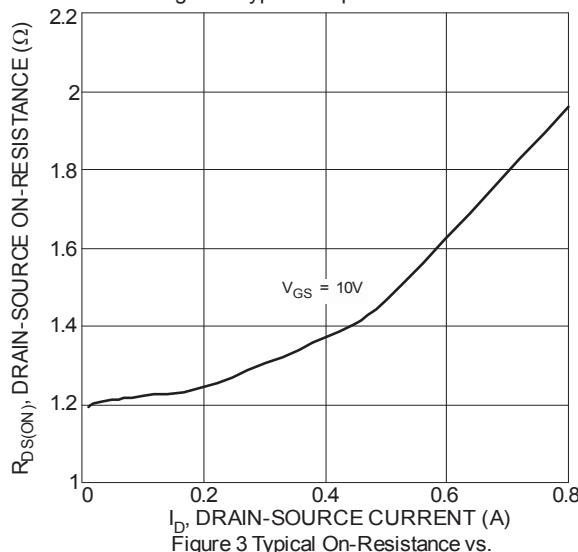
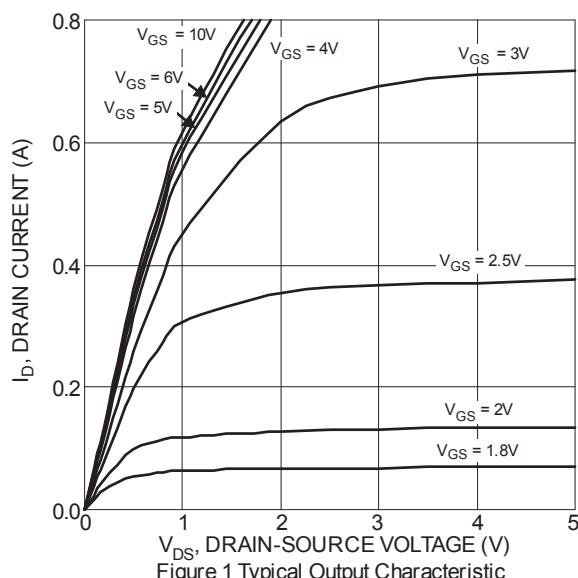
N-CHANNEL ENHANCEMENT MODE MOSFET

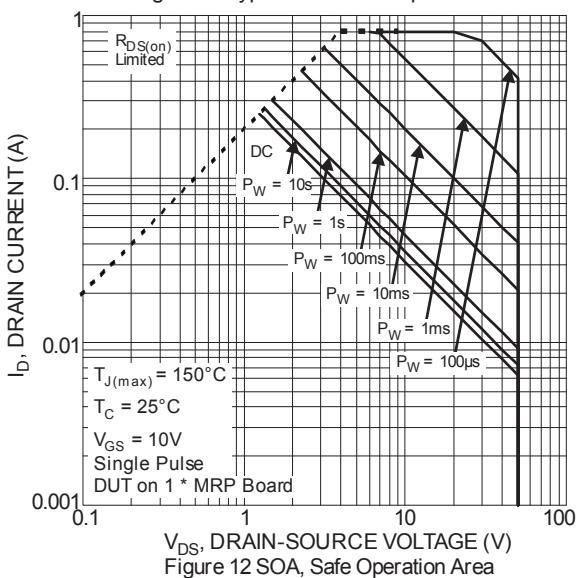
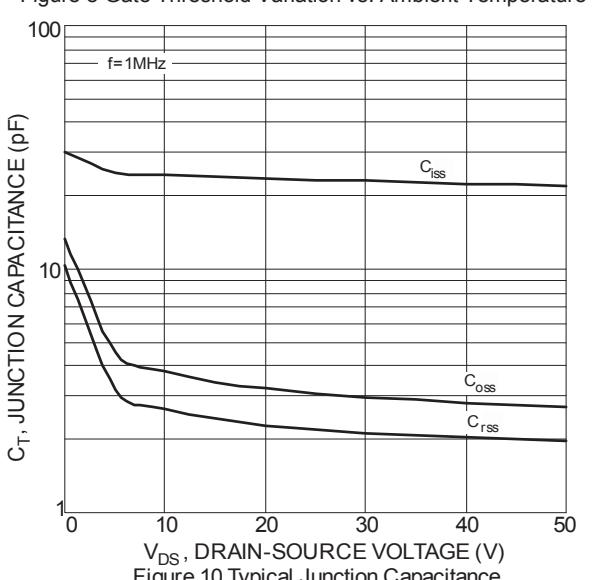
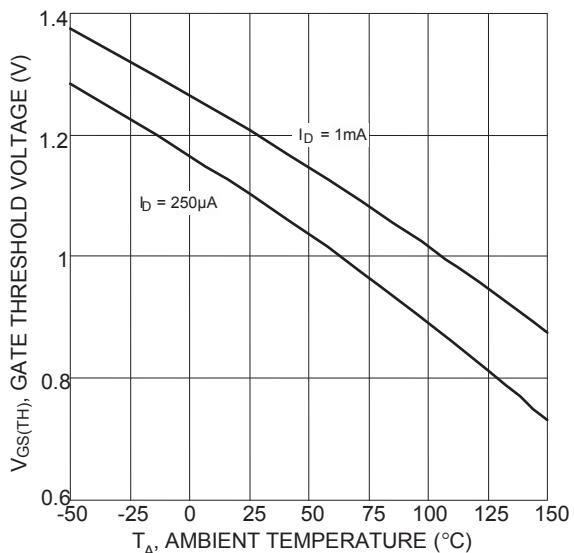
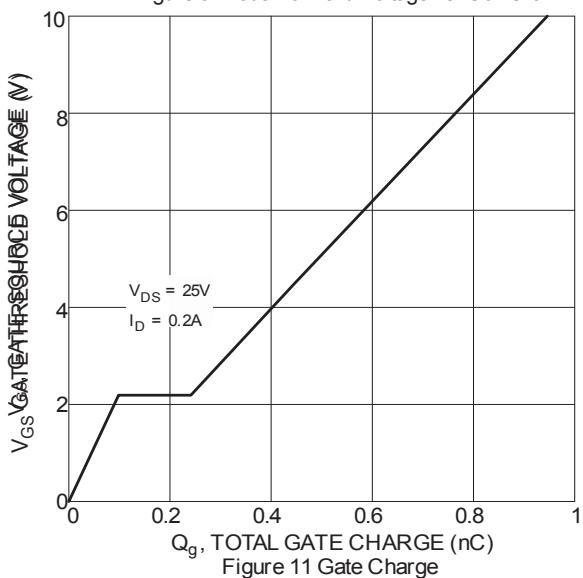
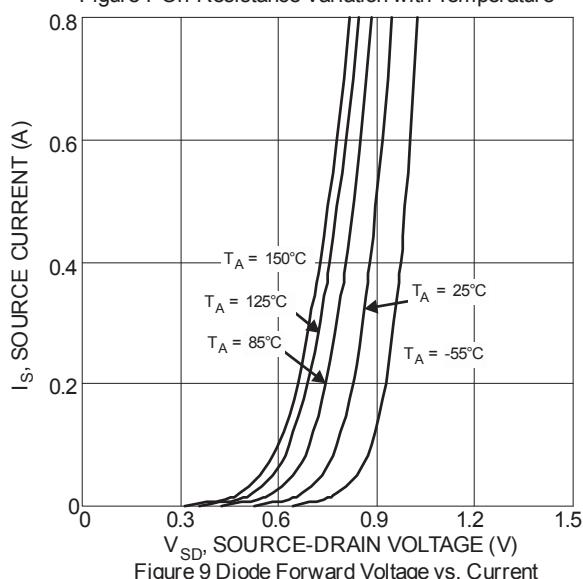
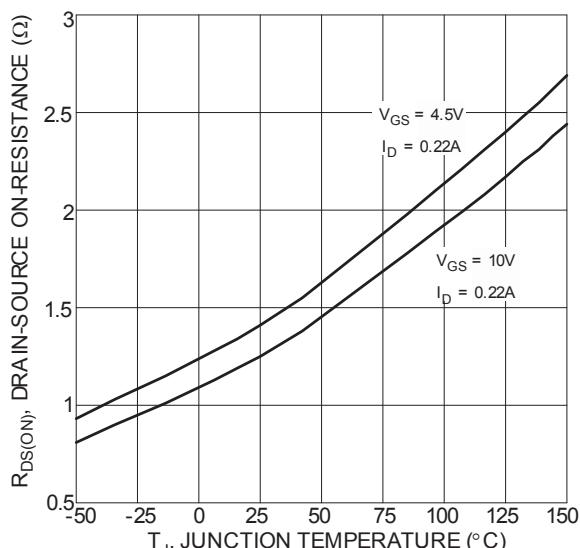
Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|----------------------------|---|-----|------|----------|---------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 50 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}$ | | | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$ | | | ± 10 | μA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$ | 0.5 | 0.85 | 1.2 | V |
| Drain-Source On-State Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=0.20\text{A}$ | | 1.5 | 2.5 | Ω |
| | | $V_{\text{GS}}=10\text{V}, I_{\text{D}}=0.22\text{A}$ | | 1.1 | 2.0 | Ω |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=10\text{V}, I_{\text{D}}=0.2\text{A}$ | 0.2 | | | S |
| Dynamic Characteristics (Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$ | | 30 | | PF |
| Output Capacitance | C_{oss} | | | 15 | | PF |
| Reverse Transfer Capacitance | C_{rss} | | | 6 | | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}}=30\text{V}, I_{\text{D}}=0.22\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=6\Omega$ | | | 5 | nS |
| Turn-on Rise Time | t_r | | | | 5 | nS |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | | | 60 | nS |
| Turn-Off Fall Time | t_f | | | | 35 | nS |
| Total Gate Charge | Q_g | $V_{\text{DS}}=25\text{V}, I_{\text{D}}=0.2\text{A}, V_{\text{GS}}=10\text{V}$ | | | 2.4 | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | $V_{\text{GS}}=0\text{V}, I_{\text{S}}=0.22\text{A}$ | | | 1.3 | V |
| Diode Forward Current (Note 2) | I_{S} | | | | 0.22 | A |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

TYPICAL TRANSIENT CHARACTERISTICS


TYPICAL TRANSIENT CHARACTERISTICS


TYPICAL TRANSIENT CHARACTERISTICS

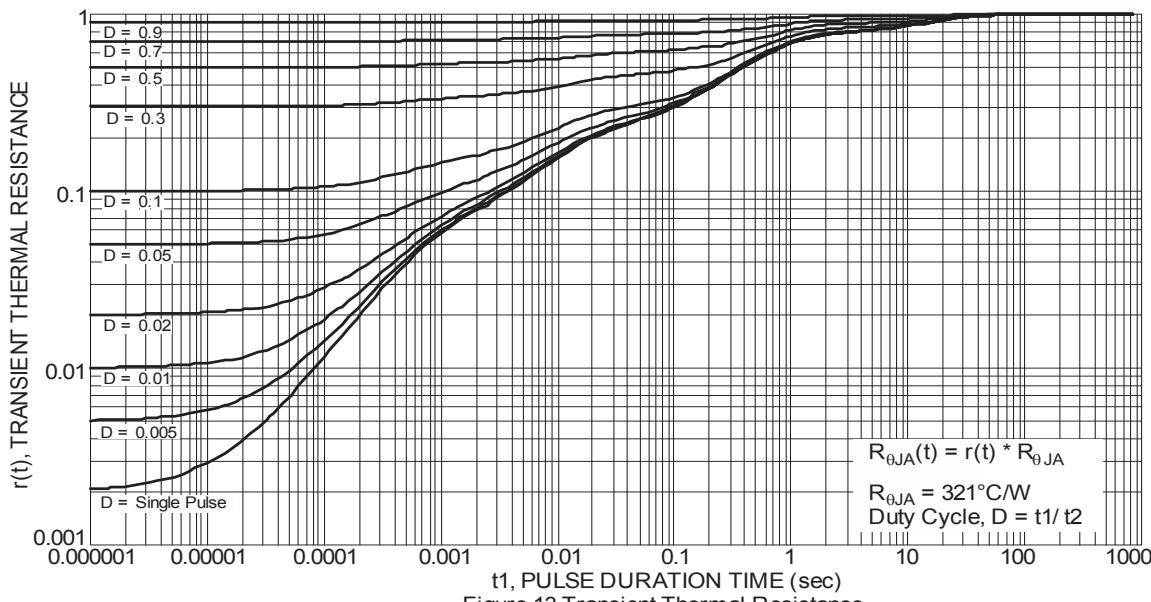


Figure 13 Transient Thermal Resistance



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N-CHANNEL ENHANCEMENT MODE MOSFET

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